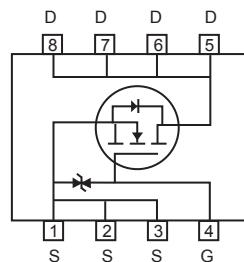
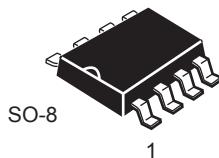


## N-Channel Enhancement Mode Field Effect Transistor

PRELIMINARY

## FEATURES

- 20V, 9.3A,  $R_{DS(ON)} = 18m\Omega$  @ $V_{GS} = 4.5V$ .  
 $R_{DS(ON)} = 24m\Omega$  @ $V_{GS} = 2.5V$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- Lead-free plating ; RoHS compliant.
- Surface mount Package.

ABSOLUTE MAXIMUM RATINGS  $T_A = 25^\circ C$  unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current-Continuous	$I_D$	9.3	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	37.2	A
Maximum Power Dissipation	$P_D$	2.5	W
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ C$

## Thermal Characteristics

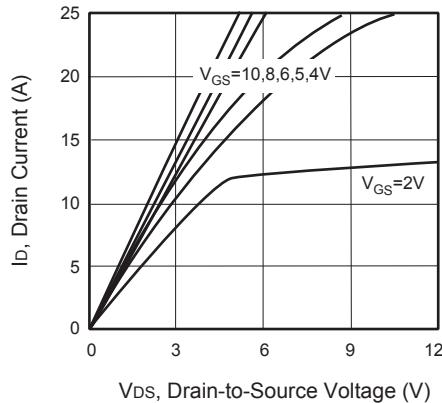
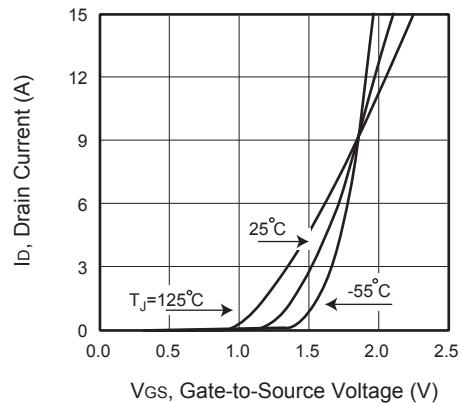
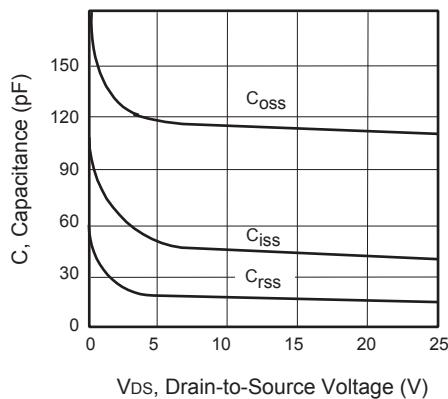
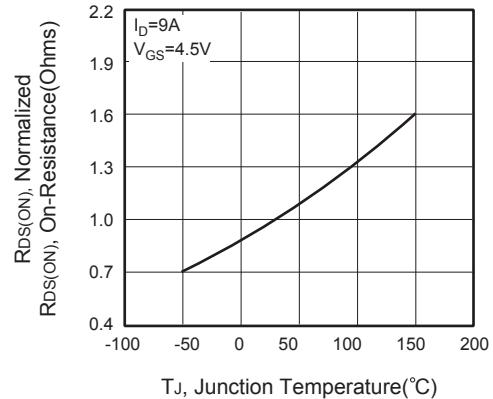
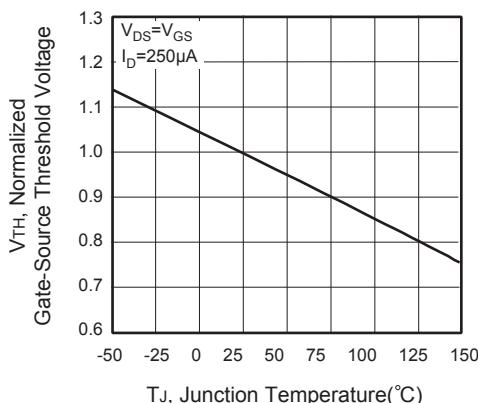
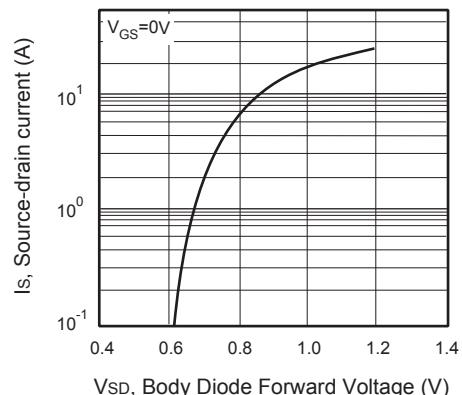
Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{\theta JA}$	50	$^\circ C/W$

**CEM2182****Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	20			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 12\text{V}, V_{\text{DS}} = 0\text{V}$			10	$\text{uA}$
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -12\text{V}, V_{\text{DS}} = 0\text{V}$			-10	$\text{uA}$
<b>On Characteristics<sup>c</sup></b>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	0.3		1	V
Static Drain-Source	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 9\text{A}$		14	18	$\text{m}\Omega$
On-Resistance		$V_{\text{GS}} = 2.5\text{V}, I_D = 4.5\text{A}$		17	24	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>d</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		40		pF
Output Capacitance	$C_{\text{oss}}$			115		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			15		pF
<b>Switching Characteristics<sup>d</sup></b>						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 10\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 4.5\text{V}, R_{\text{GEN}} = 6\Omega$		0.34		$\mu\text{s}$
Turn-On Rise Time	$t_r$			0.68		$\mu\text{s}$
Turn-Off Delay Time	$t_{\text{d(off)}}$			3.58		$\mu\text{s}$
Turn-Off Fall Time	$t_f$			2		$\mu\text{s}$
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 15\text{V}, I_D = 7\text{A}, V_{\text{GS}} = 4.5\text{V}$		4.2		nC
Gate-Source Charge	$Q_{\text{gs}}$			1.0		nC
Gate-Drain Charge	$Q_{\text{gd}}$			2.4		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current <sup>b</sup>	$I_S$				2	A
Drain-Source Diode Forward Voltage <sup>c</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 2\text{A}$			1.2	V

## Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Surface Mounted on FR4 Board, t ≤ 10 sec.
- c.Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
- d.Guaranteed by design, not subject to production testing.

**Figure 1. Output Characteristics****Figure 2. Transfer Characteristics****Figure 3. Capacitance****Figure 4. On-Resistance Variation with Temperature****Figure 5. Gate Threshold Variation with Temperature****Figure 6. Body Diode Forward Voltage Variation with Source Current**

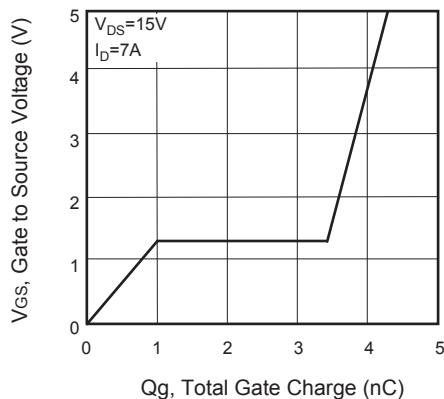


Figure 7. Gate Charge

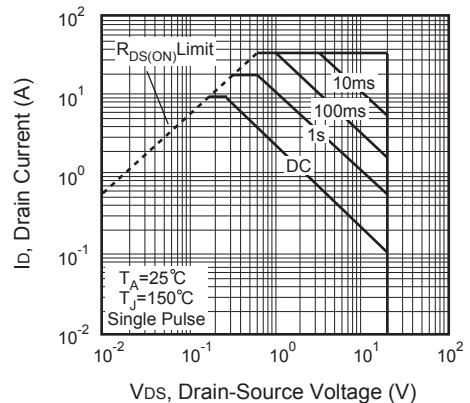


Figure 8. Maximum Safe Operating Area

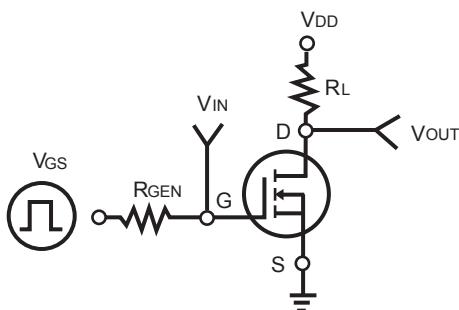


Figure 9. Switching Test Circuit

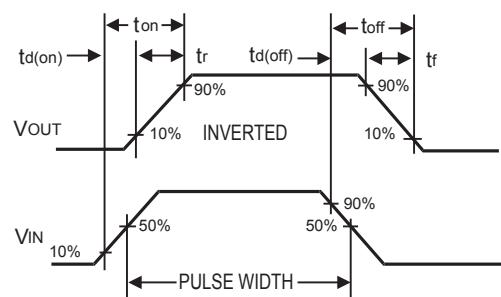


Figure 10. Switching Waveforms

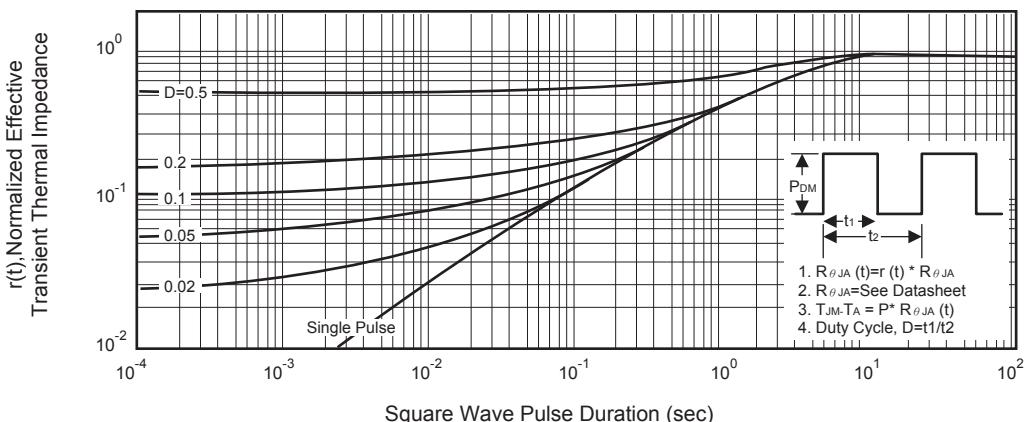


Figure 11. Normalized Thermal Transient Impedance Curve